

SILVACO

Complex device design using predictive modelling

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Silvaco at a Glance



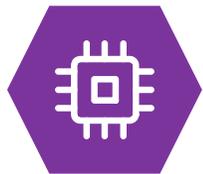
600+
Customers
Worldwide



200+
University Customers
Worldwide



260+
Employees



#1
TCAD and Modeling
for **Flat Panel, Power**



Solutions for
Display, EV Power, SoC, IoT,
Fab Process Optimization



Deep Industry &
Academic
Collaborations

De-risking technology development



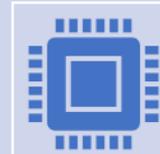
To develop technology, we need design tools.



Automation design software sits at the heart of this development. Essential part of the supply chain.

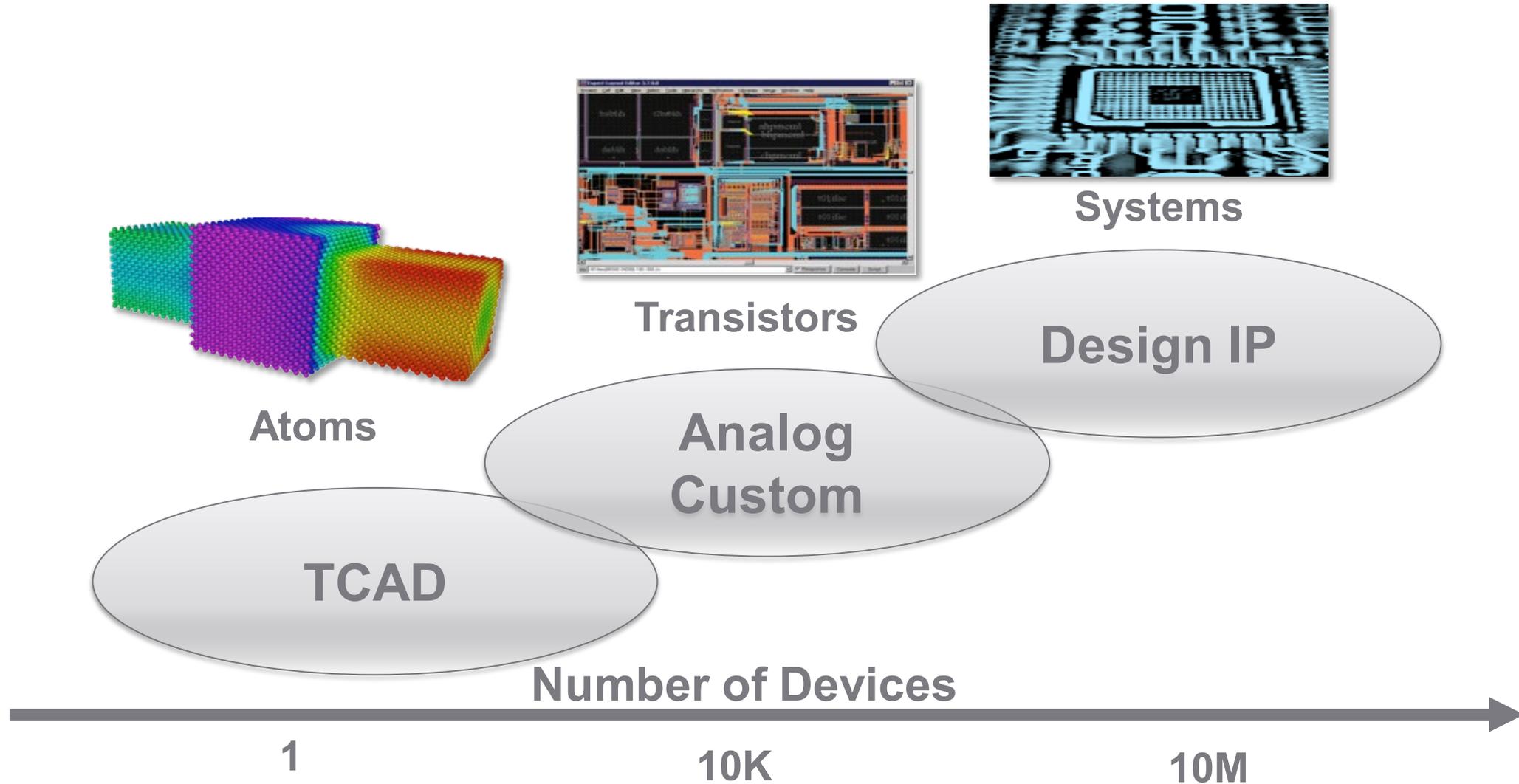


Predictive modelling is attractive; however, it comes at a great cost!



Move to circuits and system design will happen when devices “just work”.

Silvaco's Solution Spectrum



Power Device Technology

Market, R&D Drivers

- **New Device Geometries**

- Exploiting 3D material properties to maximize performance/power density
- Novel layouts to increase device density

- **Next Generation Materials**

- SiC, GaN - Inherently better performance to challenge existing silicon-based designs
- New electrical and fabrication behaviors to understand and improve

Power Device Technology

Market, R&D Drivers

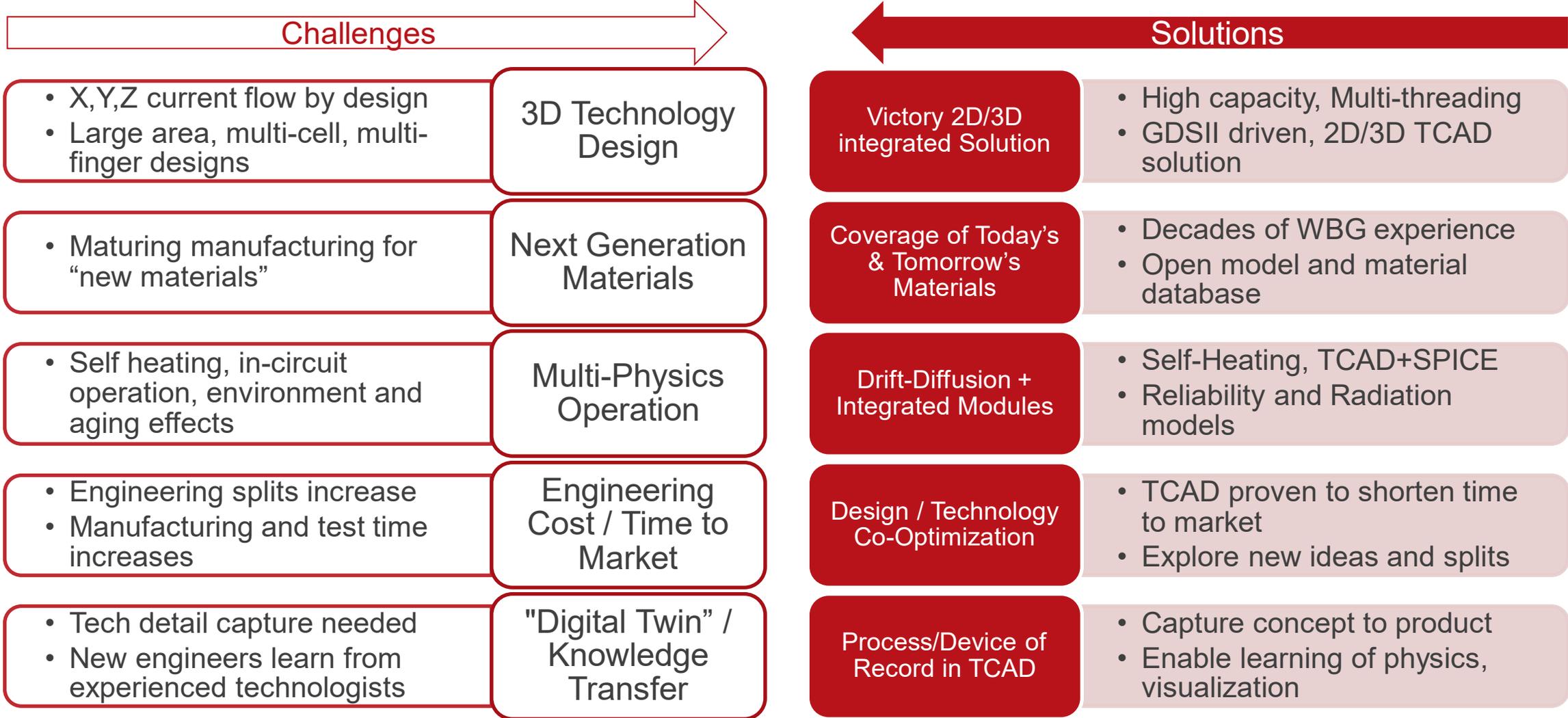
- **High Demand for Power Devices**

- Higher volume applications (e.g., Electric Vehicles) require scaling of semiconductor technologies with high yield

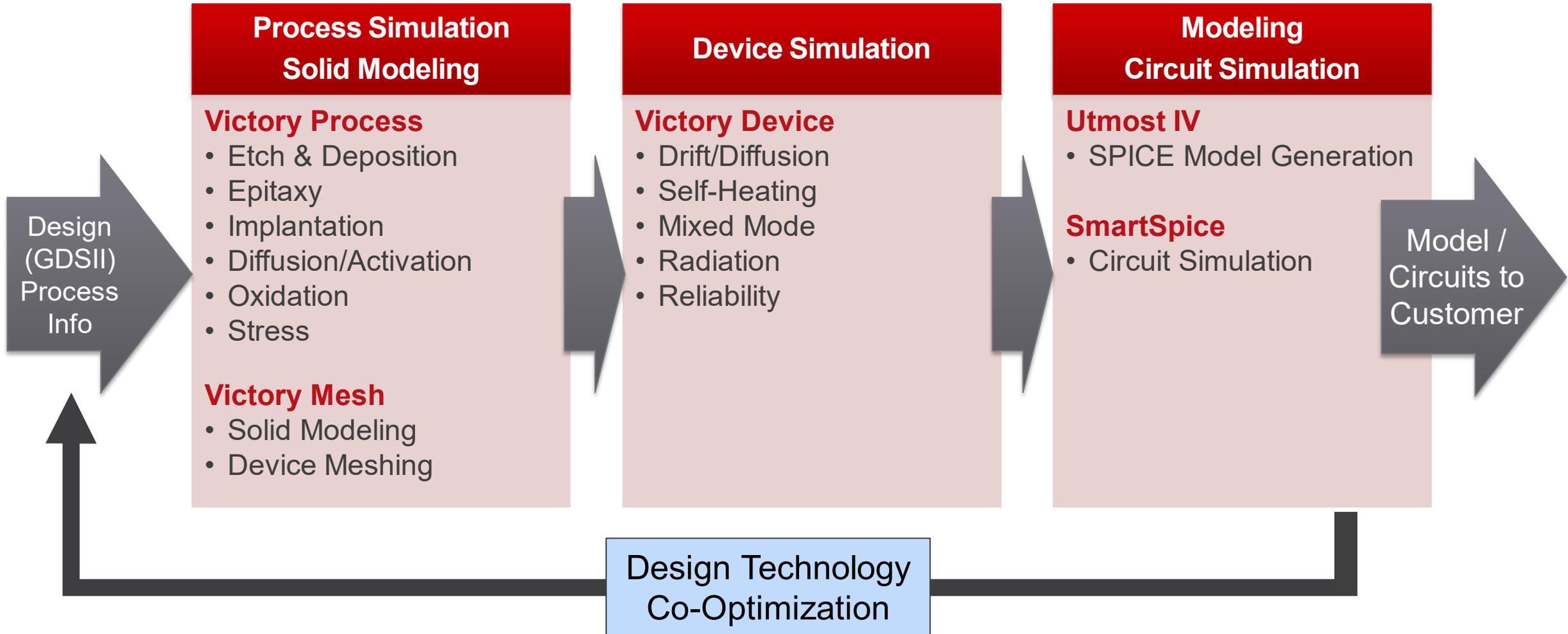
- **Reliable by Design**

- In-depth physics understanding required to meet standards of end use applications (e.g., Automotive, Mil/Aero/Space)

Challenges & Silvaco Solutions



Victory TCAD Solution for Power Devices



Victory Process for Si & SiC Power Devices

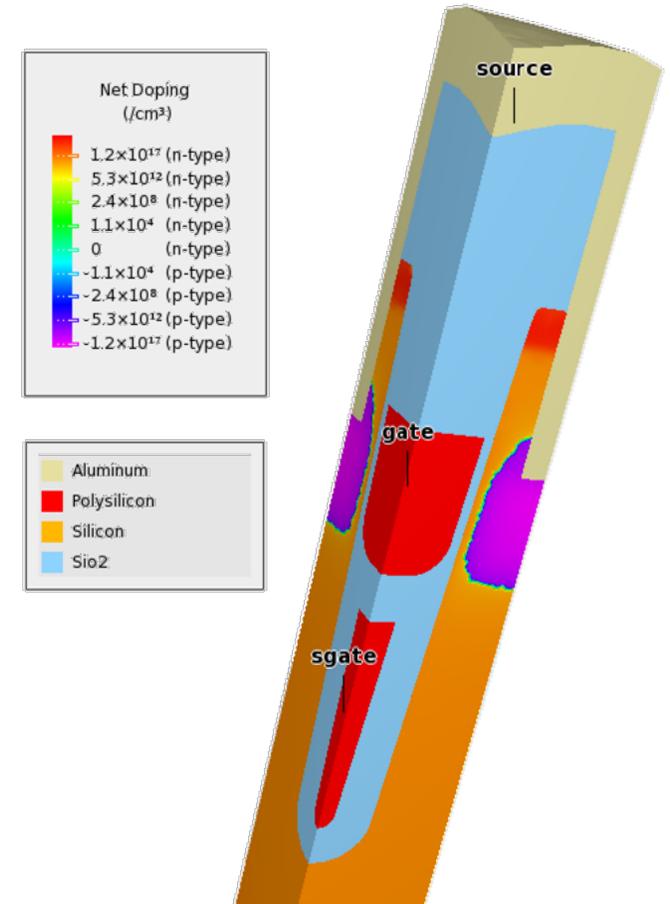
Virtualize your process flow. Optimize the next generation power devices through virtual fabrication

Full 2D/3D TCAD Process Solution

- Build, debug, calibrate in fast 2D
- Easy transition to realistic 3D for full 3D technology design
- Seamless integration into Device Simulation

Process simulation for Si and SiC

- Etch & Deposition
- Implantation
- Dopant Activation
- Oxidation
- Open Model Library and Material database
 - Allows for user customizability

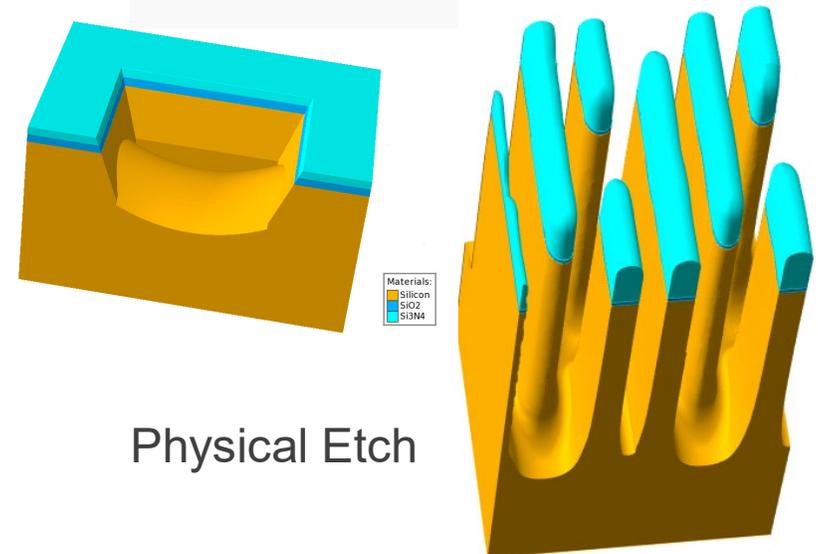
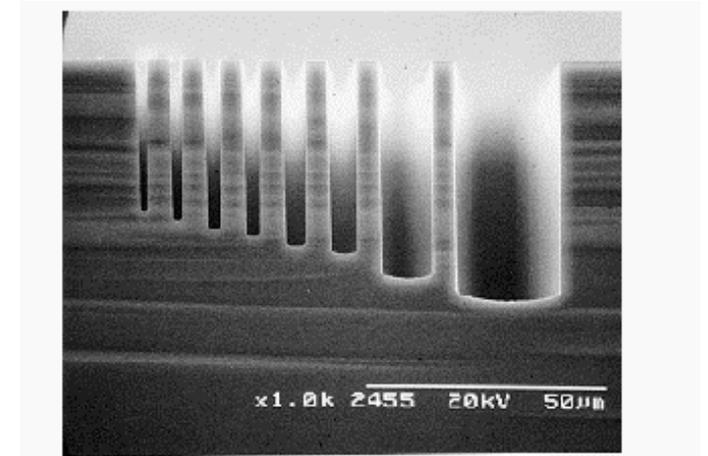


Silicon Split Gate Trench UMOSFET from Victory Process

Etch & Deposition for Next Generation Devices

New power devices utilize multiple etch and deposition steps to produce trenches, spacers, and dielectric layers. Capturing material geometry faithfully ensures TCAD simulation matches the fab.

- **GDSII driven TCAD**, connecting fab to TCAD
 - Import layout to use as masks for any process step
- **Simple geometric models** for fast simulating etch & deposition steps
 - Define etch/deposition thicknesses and a geometric model
- **Detailed physical models** for deeper understanding of your process steps
 - Define deposition/etch rates for each material
 - Sticking factors, flux parameters
 - Useful for understand visibility effects



Implantation Accuracy with Victory Process

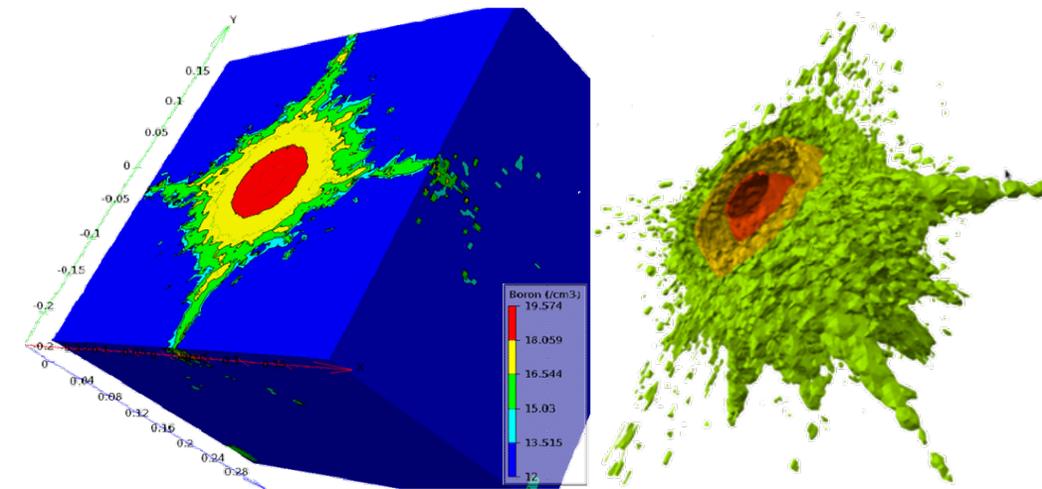
Fabrication processes include numerous implantations steps. Capturing physics-accurate implantation profiles allows optimization of process conditions for the best performing, high yield devices

Physical Implantation via Monte Carlo Implantation

- User-Definable Implant Properties
 - Substrate type/orientation, wafer miscut, angle, dose and energy
- Well calibrated stopping within crystal channels and random direction
 - Crystal Damage & Scattering due to damage accumulation

Empirical Methods to define doping in process

- Doping profiles by analytical distribution function
 - Quickly add Gaussian doping
- Doping profiles defined by external data files
 - Use SIMS profiles to build your TCAD process



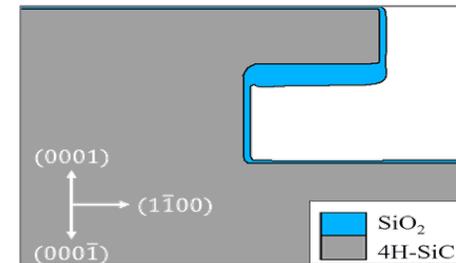
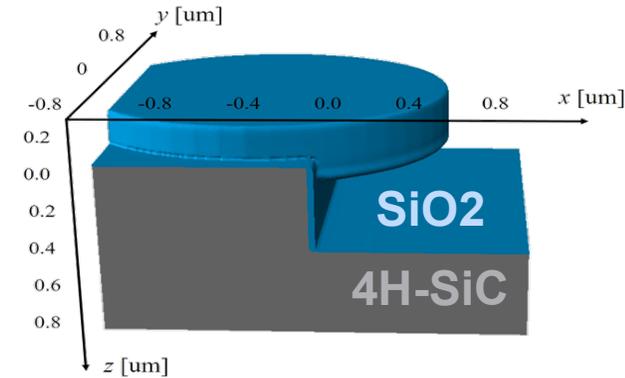
Implant distribution at the Silicon surface shows pronounced lateral channeling

Robust Oxidation Simulation

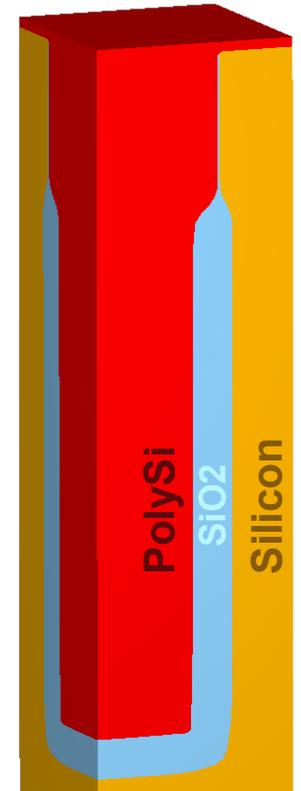
Simulation of 3D oxidation is a challenging numerical problem. Victory Process is capable of efficiently and accurately modeling key oxidation steps for Silicon and Silicon Carbide devices.

Oxidation Simulations available for Si & SiC

- Well calibrated for Silicon & Silicon Carbide
- Fully 3D Anisotropic Oxidation Model for 4H-SiC
 - Each crystal plane will have separate oxidation rates
 - Well calibrated to experimental results
 - Useful for understanding oxidation in trench devices



Anisotropic Oxidation Effects for 4H-SiC



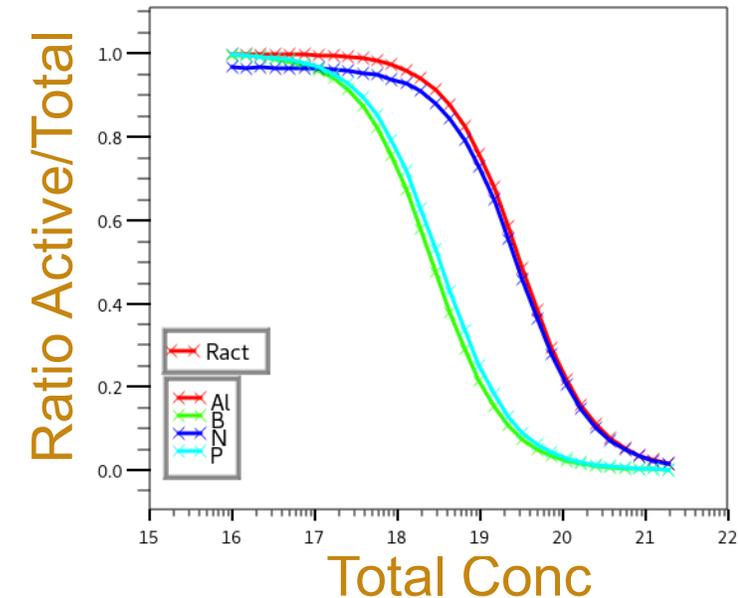
LOCOS Oxidation for Silicon Power Device

Electrical Activation During Fabrication

Incomplete activation of dopants can dictate device performance, especially in Silicon Carbide. Modeling electrical activation as part of process simulation captures dopant concentrations accurately

Dopant Activation Models calibrated for both Si & SiC

- Two major activation models: Empirical and Transient
 - **Empirical:** Instantaneous relationship between active and non-active concentrations
 - **Transient:** Adds transient partial differential equation to the empirical model
- **Table Method** for inserting user input data
 - Allows users to incorporate proprietary or new experimental activation data with ease



Activation Ratio vs Concentration for 4H-SiC at 1700C

Victory Device for Si & SiC Power Devices

Victory Device meets the breadth and depth of power device simulation needs

Simulate DC, AC and transient electrical simulation

- Understand how your device performs in any scenario

Self-Heating Simulation

- Gain insight into self-heating effects that influences electrical physics

Reliability and Radiation

- Simulate device degradation due to electrical stress, as well as radiation effects (TID, DD, SEB)

MixedMode circuit/device simulation

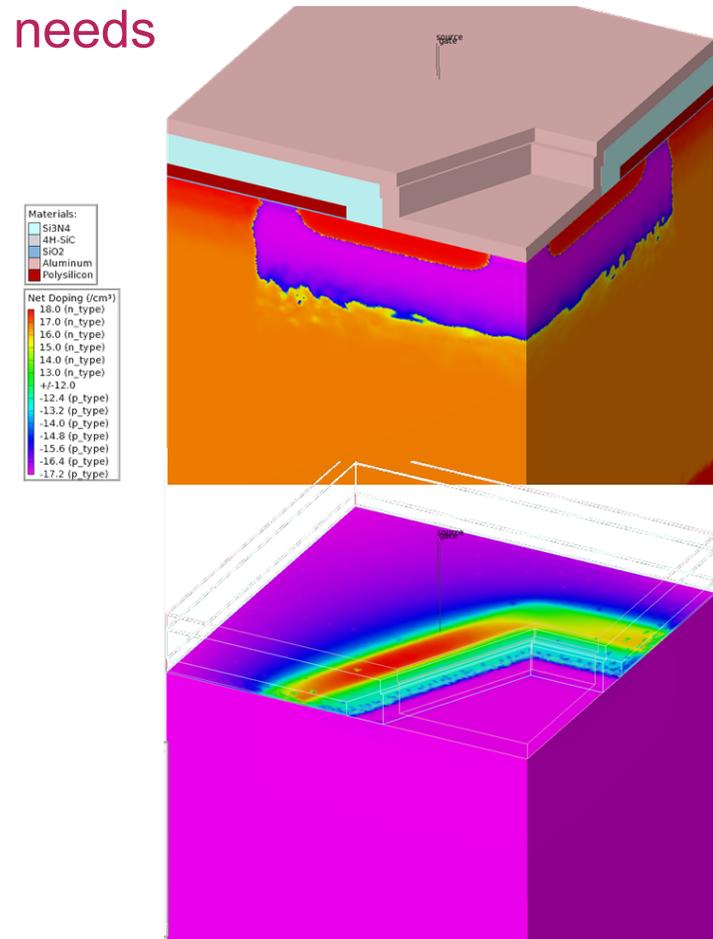
- Simulate TCAD devices within a SPICE circuit

User-customizable physical models & material parameters

- Calibrate any simulated device to your experimental data
- Novel wide bandgap materials can be simulated by adjusting the physical parameters

Advance numerical solvers and methods

- Multithreaded simulations and numerical extended precision available for the more difficult simulations



Anisotropic Mobility of SiC HexFET

Summary

- **Multiscale flow**
 - Automated flow from process to circuit design.
 - Multiphysics is essential for mature technology design.
- **Design Space Exploration**
 - TCAD & EDA tools are essential for optimizing technology performance.
 - Increasing complexity requires advanced numerical methods.
- **Ramping up R&D**
 - Design software provides insight.
 - Generate deep understanding of technology potential.
 - Safeguard company knowledge and IP.

Silvaco is leading the way for next generation Power Device Technology simulation

